

har-flex f str6.25 SnapIn 50p PL1 280pcs



Image is for illustration purposes only. Please refer to product description.

Part number	15 21 050 2620 000
Specification	har-flex f str6.25 SnapIn 50p PL1 280pcs
HARTING eCatalogue	https://harting.com/15210502620000

Identification

Category	Connectors
Series	har-flex®
Identification	Signal
Element	Female connector
Specification	with locking function for adapter
Description of the contact	Straight

Version

Termination method	Reflow soldering termination (SMT)
Connection type	Motherboard to daughtercard Mezzanine
Number of contacts	50
Pack contents	280 pieces on reel

Technical characteristics

Contact rows	2
Contact spacing (termination side)	1.27 mm
Contact spacing (mating side)	1.27 mm
Stacking height	6.25 mm
Clearance distance	≥0.4 mm
Creepage distance	≥0.4 mm
Insulation resistance	>10 ⁹ Ω
Contact resistance	<25 mΩ

Technical characteristics

Limiting temperature	-55 ... +125 °C
Insertion force	≤40 N
Withdrawal force	≥7.5 N ≤35 N
Performance level	1
Mating cycles	≥500
Test voltage $U_{r.m.s.}$	0.5 kV
Isolation group	IIIa (175 ≤ CTI < 400)
Moisture Sensitivity Level (MSL)	1 acc. to ECA/IPC/JEDEC J-STD-020D
Process Sensitivity Level (PSL)	R0 acc. to ECA/IPC/JEDEC J-STD-075
Coplanarity of contacts	≤0.12 mm

Material properties

Material (insert)	Liquid crystal polymer (LCP)
Material (contacts)	Copper alloy
Surface (contacts)	Noble metal over Ni Mating side Sn over Ni Termination side
Material flammability class acc. to UL 94	V-0
RoHS	compliant
ELV status	compliant
China RoHS	e
REACH Annex XVII substances	Not contained
REACH ANNEX XIV substances	Not contained
REACH SVHC substances	Not contained
California Proposition 65 substances	Not contained

Specifications and approvals

UL / CSA	UL in preparation
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Commercial data

Packaging size	280
Net weight	1.289 g
Country of origin	China
European customs tariff number	85366990
GTIN	5713140846586

Commercial data

eCl@ss 27460201 PCB connector (board connector)

ETIM EC002637

UNSPSC 24.0 39121415

RECOMMENDATION FOR SOLDER PROCESSING

Solder paste recommendation

The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb40

PCB pad plating

The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn.

Stencil recommendation

The solder deposition has to be placed on the pad area of the contact solder tines.

Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads.

The size of the solder stencil apertures is depending on the thickness of the stencil.

In general, the thinner stencils will need larger apertures to result in the required volume of solder paste.

The minimum required solder paste volume for the signal pins is 0,094mm³, for the hold down it is 0,33mm³.

For example, this can be achieved with the following stencil data :

Signal pins			
Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume
120 µm	1,1 x 0,8 mm	1,05 x 0,75 mm	0,095 mm ³
150 µm	1,1 x 0,8 mm	0,99 x 0,72 mm	0,107 mm ³

Hold-downs			
Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume
120 µm	2,5 x 1,2 mm	2,45 x 1,15 mm	0,338 mm ³
150 µm	2,5 x 1,2 mm	2,25 x 1,08 mm	0,365 mm ³

If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging the stencil aperture. Depending on the PCB design, the solder deposition may protrude the PCB pads. But to achieve a good sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.